AMENDMENTS TO THE SPECIFICATION

Please replace the second and third paragraphs on page 6 as follows:

Fig. 2 is a cross sectional view which schematically shows an example of a prepreg according to the present invention, on which a metallic foil is bonded; and

Fig. 3 is a side view which schematically shows an example of a semiconductor package according to the present invention[[;]] .

After the third paragraph on page 6, please delete the following paragraphs in their entirety:

~~Fig. 4 is a Table 1 which shows the results of evaluation tests;~~

~~Fig. 5 is a Table 2 which shows the results of evaluation tests; and~~

~~Fig. 6 is a Table 3 which shows the results of evaluation tests.~~

Please replace the first line at the top of page 33 as follows:

Evaluation results are shown in Table 1 as follows: ~~in Fig. 4~~.

Table 1

		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
First resin	PRIMASET PT-60	10	13	10	10	
	PRIMASET PT-60A					10
Second resin	PRIMASET PT-30	10	13	10	10	10
	LACY					
Resin having low moisture absorbency	NC-3000SH	12	8	12	12	12
	ARTON					
Curing agent	MEH-7851-3H	8	6	8	8	8
	PR-51714					
Filler	SFP-10X	60	60	60	60	60
	FB-5SDX					
	AO-802					
Reaction rate (%)		5	5	20	30	5
Evaluations	Flexibility	A	A	A	A	B
	Development of tack	A	A	A	A	A
	Generation of dust	A	A	A	B	A
	Resin flow (%)	15	20	12	10	10
	Processability with laser	B	B	B	B	B

		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
First resin	PRIMASET PT-60	10	18.5	5	10	15
	PRIMASET PT-60A					
Second resin	PRIMASET PT-30		1.5	15	10	15
	LACY	10				
Resin having low moisture absorbency	NC-3000SH	12	12	12		6
	ARTON				12	
Curing agent	MEH-7851-3H	8	8	8	8	4
	PR-51714					
Filler	SFP-10X	60	60	60	60	60
	FB-5SDX					
	AO-802					
Reaction rate (%)		5	5	5	5	5
Evaluations	Flexibility	A	B	A	A	A
	Development of tack	B	A	B	A	A
	Generation of dust	A	B	A	A	A
	Resin flow (%)	20	12	18	20	20
	Processability with laser	B	B	B	B	B

Table 1 (continued)

		Ex.11	Ex.12	Ex.13	Ex.14	Ex.15
First resin	PRIMASET PT-60	10	10	10	14	10
	PRIMASET PT-60A					
	NC-3000SH					
Second resin	PRIMASET PT-30	10	10	10	14	10
	LACY					
	EP-830					
Resin having low moisture absorbency	NC-3000SH	12	12	12	17	12
	ARTON					
Curing agent	MEH-7851-3H		8	8	11	8
	PR-51714	8				
Filler	SFP-10X	60			44	60
	FB-5SDX		60			
	AO-802			60		
Reaction rate (%)		5	5	5	5	5
Evaluations	Flexibility	A	A	A	A	A
	Development of tack	A	A	A	B	A
	Generation of dust	A	A	A	A	A
	Resin flow (%)	12	5	15	25	15
	Processability with laser	B	B	B	B	A

		Ex.16	Com.1	Com.2	Com.3	Com.4
First resin	PRIMASET PT-60		20		25	10
	PRIMASET PT-60A					
	NC-3000SH	22				
Second resin	PRIMASET PT-30			20	25	10
	LACY					
	EP-830	10				
Resin having low moisture absorbency	NC-3000SH		12	12	30	20
	ARTON					
Curing agent	MEH-7851-3H	8	8	8	20	
	PR-51714					
Filler	SFP-10X	60	60	60		60
	FB-5SDX					
	AO-802					
Reaction rate (%)		5	5	5	5	5
Evaluations	Flexibility	A	D	A	A	A
	Development of tack	A	A	D	C	A
	Generation of dust	A	D	A	A	A
	Resin flow (%)	25	15	15	40	25
	Processability with laser	A	B	B	B	B

Please replace the fourth paragraph on page 35 as follows:

As shown in Table 1 ~~in Fig. 4~~, each of the prepregs prepared in Examples 1 to 16 had excellent flexibility. Further, each of the prepregs prepared in Examples 1 to 5, 7, 9 to 13, 15, and 16 had especially little tack. Furthermore, no dust was generated from each of the prepregs prepared in Examples 1 to 3, 5, 6, and 8 to 16. Moreover, each of the prepregs prepared in Examples 15 and 16 exhibited excellent processability of via holes with laser.

Please replace the second paragraph on page 36 as follows:

For the laminates prepared in Examples 1a to 16a and Comparative Examples 1a to 4a, evaluation tests were made. Evaluation items and their details are described below. Evaluation results are shown in Table 2 as follows: ~~in Fig. 5~~.

Table 2

		Ex.1a	Ex.2a	Ex.3a	Ex.4a	Ex.5a
Prepreg		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
Evaluations	Flammability	V-0	V-0	V-0	V-0	V-0
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	>120
	Coefficient of thermal expansion (ppm)	15	13	15	15	15

		Ex.6a	Ex.7a	Ex.8a	Ex.9a	Ex.10a
Prepreg		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
Evaluations	Flammability	V-0	V-0	V-0	V-1	V-0
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	30
	Coefficient of thermal expansion (ppm)	25	13	16	17	12

		Ex.11a	Ex.12a	Ex.13a	Ex.14a	Ex.15a
Prepreg		Ex.11	Ex.12	Ex.13	Ex.14	Ex.15
Evaluations	Flammability	V-0	V-0	V-0	V-0	V-1
	Resistance to heat and moisture (sec)	30	>120	>120	>120	>120
	Coefficient of thermal expansion (ppm)	15	15	20	28	30

		Ex.16a	Com.1a	Com.2a	Com.3a	Com.4a
Prepreg		Ex.16	Com.1	Com.2	Com.3	Con.4
Evaluations	Flammability	V-1	V-0	V-0	V-1	V-1
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	10
	Coefficient of thermal expansion (ppm)	30	12	17	40	15

Please replace the third paragraph on page 37 as follows:

As is apparent from Table 2 ~~in Fig. 5~~, each of the laminates of the Examples 1a to 16a had excellent flame retardancy, and each of the laminates of Examples 1a to 8a and 9a to 14a was V-0 level in the UL-94 burning test. Further, each of the laminates of Examples 1a to 5a, 7a, 8a, and 9a to 12a had an especially low coefficient of thermal expansion.

Please replace the last paragraph on page 40 as follows:

For each of the semiconductor packages manufactured in the Examples 1b to 16b and Comparative Examples 3b and 4b, evaluation tests were made. Evaluation items and their details are described below. Evaluation results are shown in Table 3 as follows: ~~in Fig. 6~~.

Table 3

		Ex.1b	Ex.2b	Ex.3b	Ex.4b	Ex.5b
Prepreg with metallic foil		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
	Insulation resistance after humidification	0/10	0/10	0/10	0/10	0/10

		Ex.6b	Ex.7b	Ex.8b	Ex.9b	Ex.10b
Prepreg with metallic foil		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
	Insulation resistance after humidification	0/10	0/10	0/10	0/10	0/10

		Ex.11b	Ex.12b	Ex.13b	Ex.14b	Ex.15b
Prepreg with metallic foil		Ex.11	Ex.12	Ex.13	Ex.14	Ex.15
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
	Insulation resistance after humidification	0/10	0/10	0/10	0/10	0/10

		Ex.16b	Com.1b*	Com.2b*	Com.3b	Com.4b
Prepreg with metallic foil		Ex.16	Com.1	Com.2	Com.3	Com.4
Evaluations	Thermal cycling test	0/10	-	-	10/10	0/10
	Insulation resistance after humidification	0/10	-	-	0/10	5/10

* no semiconductor packages were manufactured since development of tack and generation of dust were observed in the prepregs prepared in Comparative Examples 1 and 2

Please replace the third paragraph on page 41 as follows:

As is apparent from Table 3 ~~in Fig. 6~~, all the tested samples of the semiconductor packages of Examples 1b to 16b exhibited excellent results in the thermal cycling test and the insulation resistance test, and thereby it was confirmed that they have excellent connection reliability.